

LNPT™ COLORCOMP™ COMPOUND 9X02692

DESCRIPTION

COLORCOMP 9X02692 compound is based on Polyphenylsulfone (PPSU). Added features of this grade include High Heat Resistance and Easy Processing.

| GENERAL INFORMATION | |
|-----------------------|---|
| Features | High Flow, High temperature resistance, No PFAS intentionally added |
| Fillers | Unreinforced |
| Polymer Types | Polyphenylsulfone (PPSU) |
| Processing Techniques | Injection Molding |

| INDUSTRY | SUB INDUSTRY |
|---------------------------|---------------------------------------|
| Building and Construction | Water Management |
| Consumer | Home Appliances |
| Packaging | Industrial Packaging, Food & Beverage |

TYPICAL PROPERTY VALUES

Revision 20240408

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|--|--|----------|--------------|
| MECHANICAL ⁽¹⁾ | | | |
| Tensile Modulus, 50 mm/min | 2340 | MPa | ASTM D638 |
| Tensile Stress, yld, Type I, 50 mm/min | 69.6 | MPa | ASTM D638 |
| Tensile Strain, yld, Type I, 50 mm/min | 7.2 | % | ASTM D638 |
| Tensile Strain, brk, Type I, 50 mm/min | 90 | % | ASTM D638 |
| Flexural Modulus, 1.3 mm/min, 50 mm span | 2410 | MPa | ASTM D790 |
| Flexural Stress at 5% strain, 1.3 mm/min, 50 mm span | 91 | MPa | ASTM D790 |
| IMPACT ⁽¹⁾ | | | |
| Izod Impact, notched, 23°C | 690 | J/m | ASTM D256 |
| THERMAL ⁽¹⁾ | | | |
| HDT, 1.82 MPa, 3.2mm, unannealed | 207 | °C | ASTM D648 |
| CTE, -30°C to 30°C, flow | 5.5E-05 | 1/°C | ASTM D696 |
| PHYSICAL ⁽¹⁾ | | | |
| Specific Gravity | 1.30 | - | ASTM D792 |
| Water Absorption, (23°C/24hrs) | 0.37 | % | ASTM D570 |
| Water Absorption, (23°C/Saturated) | 1.1 | % | ASTM D570 |
| Melt Flow Rate, 365°C/5.0 kgf | 17 | g/10 min | ASTM D1238 |
| Mold Shrinkage, flow ⁽²⁾ | 0.7 | % | SABIC method |
| FLAME CHARACTERISTICS | | | |
| UL Recognized, 94V-0 Flame Class Rating ⁽³⁾ | ≥0.75 | mm | UL 94 |
| FLAMMABILITY PROPERTIES | | | |
| UL Yellow Card Link ⁽³⁾ | UL Certification: E121562 - Component - Plastics | | - |
| INJECTION MOLDING ⁽⁴⁾ | | | |

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|--------------------------|----------------|-------|--------------|
| Drying Temperature | 150 | °C | |
| Drying Time | 2.5 | Hrs | |
| Maximum Moisture Content | 0.05 | % | |
| Melt Temperature | 360 – 390 | °C | |
| Mold Temperature | 140 – 160 | °C | |
| Back Pressure | 0.3 – 0.7 | MPa | |

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) UL Ratings shown on the technical datasheet might not cover the full range of thicknesses and colors. For details, please see the UL Yellow Card.
- (4) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

DISCLAIMER

Any sale by SABIC, its subsidiaries and affiliates (each a "seller"), is made exclusively under seller's standard conditions of sale (available upon request) unless agreed otherwise in writing and signed on behalf of the seller. While the information contained herein is given in good faith, SELLER MAKES NO WARRANTY, EXPRESS OR IMPLIED, INCLUDING MERCHANTABILITY AND NON-INFRINGEMENT OF INTELLECTUAL PROPERTY, NOR ASSUMES ANY LIABILITY, DIRECT OR INDIRECT, WITH RESPECT TO THE PERFORMANCE, SUITABILITY OR FITNESS FOR INTENDED USE OR PURPOSE OF THESE PRODUCTS IN ANY APPLICATION. Each customer must determine the suitability of seller materials for the customer's particular use through appropriate testing and analysis. No statement by seller concerning a possible use of any product, service or design is intended, or should be construed, to grant any license under any patent or other intellectual property right.